

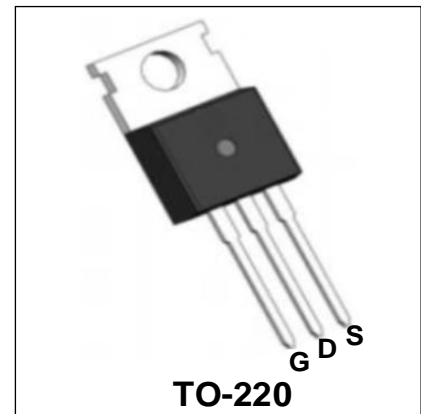
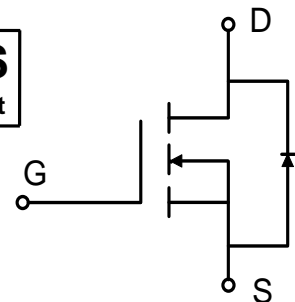
## 30V N-Channel Enhancement Mode Power MOSFET

## Description

WMK75N03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

## Features

- $V_{DS} = 30V$ ,  $I_D = 75A$   
 $R_{DS(on)} < 6m\Omega$  @  $V_{GS} = 10V$   
 $R_{DS(on)} < 9m\Omega$  @  $V_{GS} = 4.5V$
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed

RoHS  
compliant

## Applications

- Power Management Switches
- DC/DC Converter

## Absolute Maximum Ratings

Parameter		Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_C = 25^\circ C$	$I_D$	75	A
	$T_C = 100^\circ C$		47.5	
Pulsed Drain Current <sup>4</sup>		$I_{DM}$	300	A
Single Pulse Avalanche Energy <sup>3</sup>		EAS	64.8	mJ
Total Power Dissipation	$T_C = 25^\circ C$	$P_D$	59	W
Operating Junction and Storage Temperature Range		$T_J, T_{STG}$	-55 to +150	$^\circ C$

## Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	$R_{\theta JA}$	62	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	2.1	$^\circ C/W$

**Electrical Characteristics**  $T_c = 25^\circ\text{C}$ , unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	-	-	V
Gate-body Leakage current		$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	$\pm 100$	nA
Zero Gate Voltage Drain Current	$T_J=25^{\circ}C$	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1	$\mu A$
	$T_J=55^{\circ}C$			-	-	5	
Gate-Threshold Voltage		$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.0	-	2.5	V
Drain-Source On-Resistance <sup>2</sup>		$R_{DS(on)}$	$V_{GS} = 10V, I_D = 20A$	-	5	6	m $\Omega$
			$V_{GS} = 4.5V, I_D = 15A$	-	6.5	9	
Forward Transconductance		$g_{fs}$	$V_{DS}=5V, I_D=20A$	-	45	-	S
Dynamic Characteristics							
Input Capacitance		$C_{iss}$	$V_{DS} = 15V, V_{GS} = 0V, f = 1MHz$	-	1995	-	pF
Output Capacitance		$C_{oss}$		-	285	-	
Reverse Transfer Capacitance		$C_{rss}$		-	198	-	
Switching Characteristics							
Gate Resistance		$R_g$	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	-	2.0	-	$\Omega$
Total Gate Charge		$Q_g$	$V_{GS} = 4.5V, V_{DS} = 15V, I_D = 15A$	-	19	-	nC
Gate-Source Charge		$Q_{gs}$		-	7.7	-	
Gate-Drain Charge		$Q_{gd}$		-	7	-	
Turn-On Delay Time		$t_{d(on)}$	$V_{GS} = 10V, V_{DD} = 15V, R_G = 3.3\Omega, I_D = 15A$	-	7.9	-	ns
Rise Time		$t_r$		-	14.8	-	
Turn-Off Delay Time		$t_{d(off)}$		-	37	-	
Fall Time		$t_f$		-	10.4	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage <sup>2</sup>		$V_{SD}$	$I_S = 1A, V_{GS} = 0V$	-	-	1	V
Continuous Source Current <sup>1,5</sup>		$I_S$	$V_G=V_D=0V$ , Force Current	-	-	75	A
Body Diode Reverse Recovery Time		$t_{rr}$	$I_F = 20A, dI/dt = 100A/\mu s$	-	15	-	ns
Body Diode Reverse Recovery Charge		$Q_{rr}$		-	5.5	-	nC

## Notes:

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- The EAS data shows Max. rating. The test condition is  $V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 36A$
- Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)} = 150^\circ\text{C}$ .
- The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

## Typical Characteristics

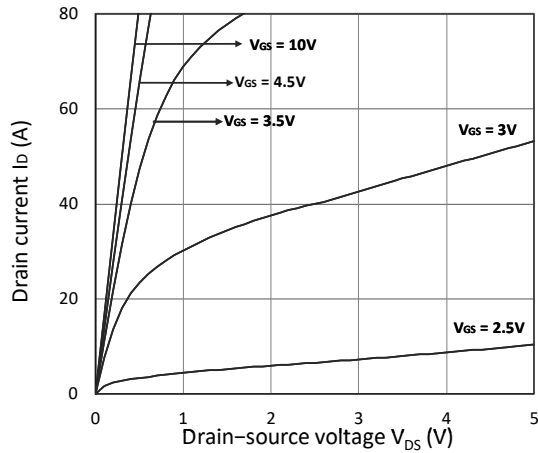


Figure 1. Output Characteristics

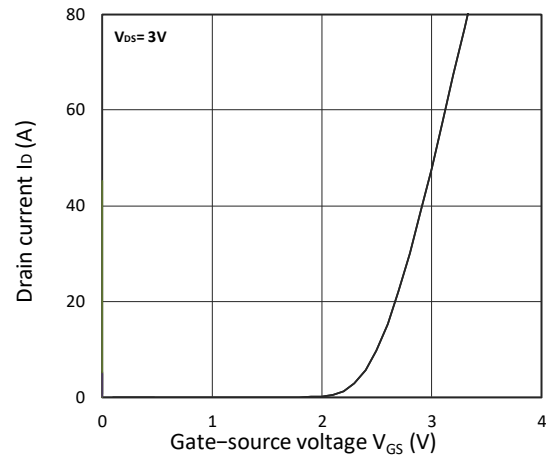


Figure 2. Transfer Characteristics

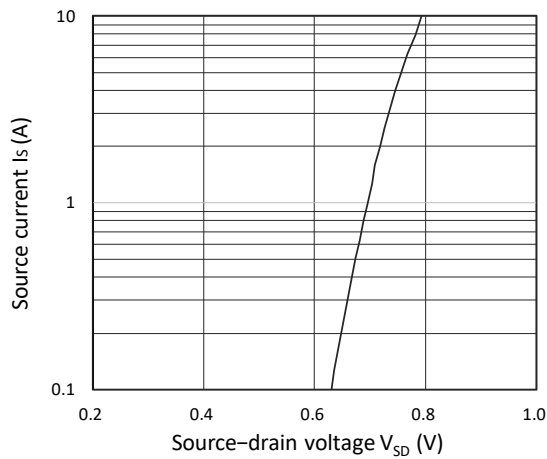
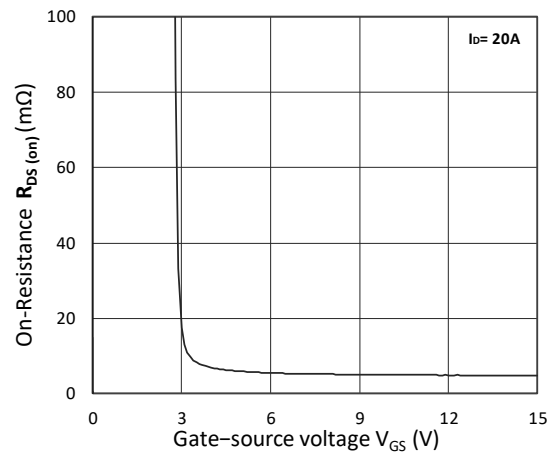
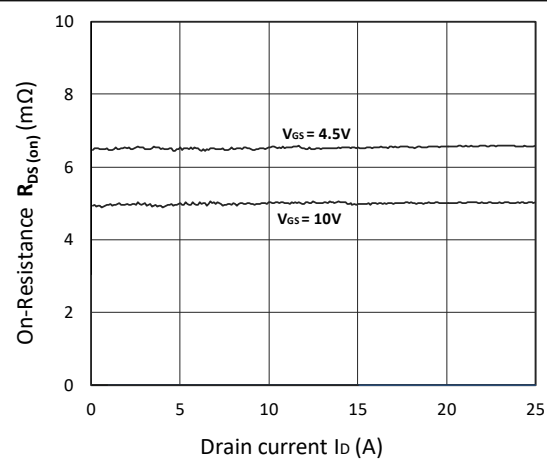
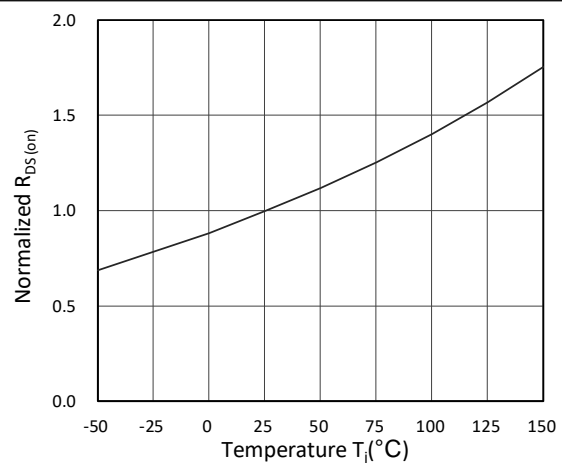


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(on)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(on)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature

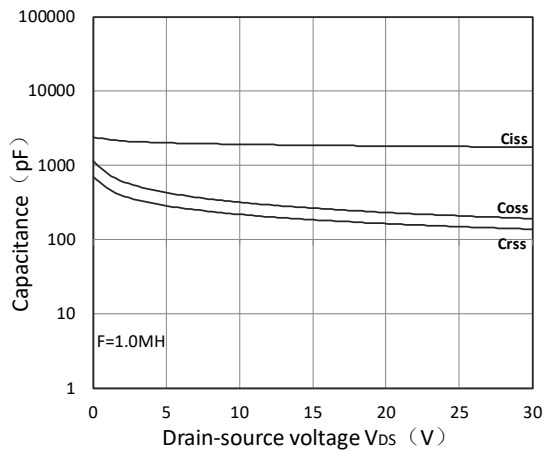


Figure 7. Capacitance Characteristics

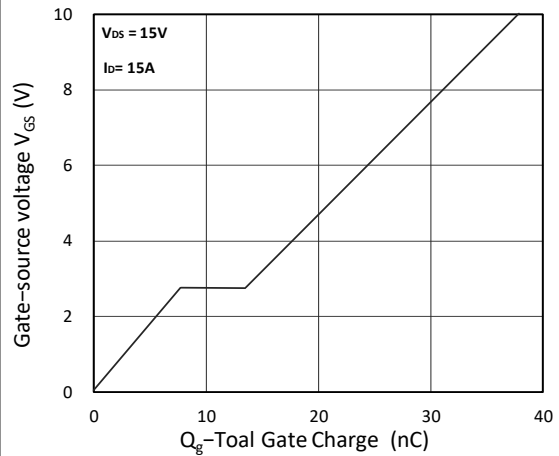


Figure 8. Gate Charge Characteristics

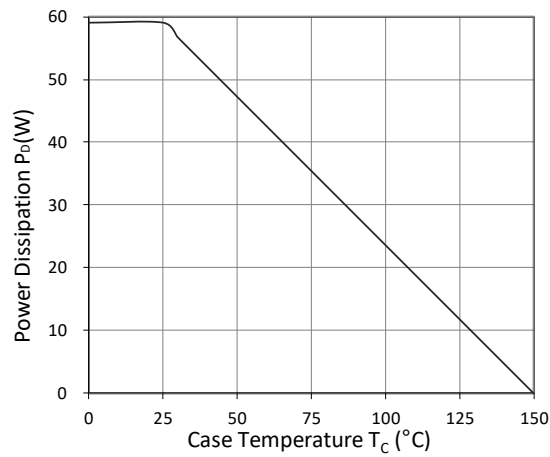


Figure 9. Power Dissipation

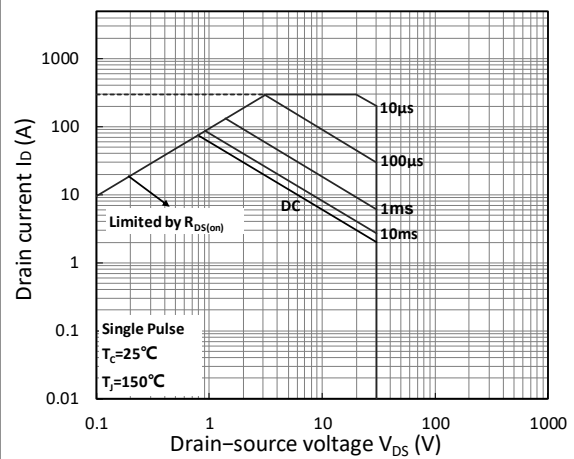


Figure 10. Safe Operating Area

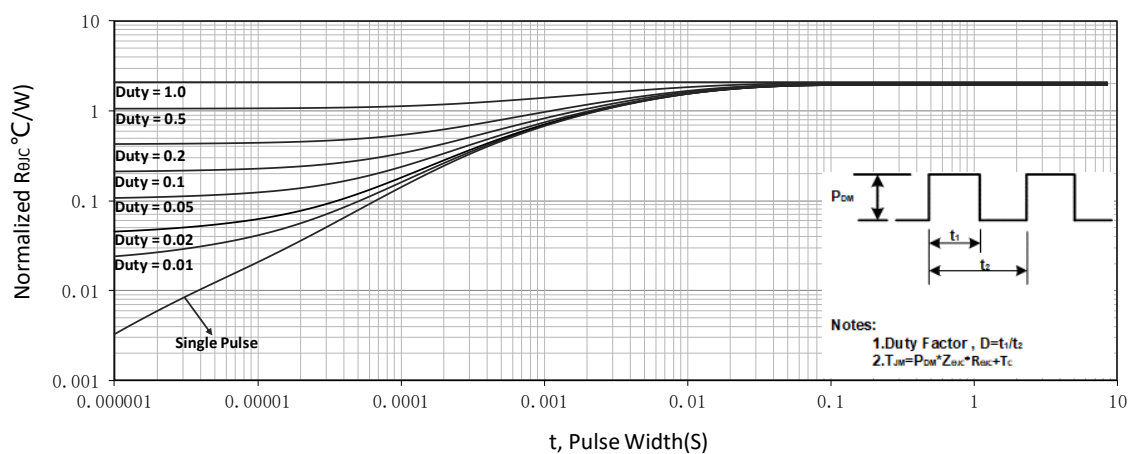


Figure 11. Normalized Maximum Transient Thermal Impedance

## Test Circuit

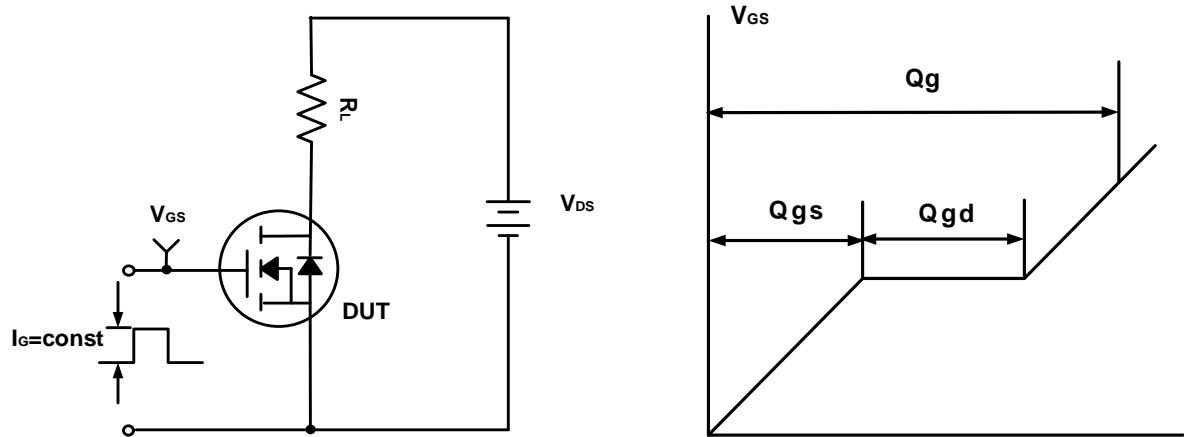


Figure A. Gate Charge Test Circuit &amp; Waveforms

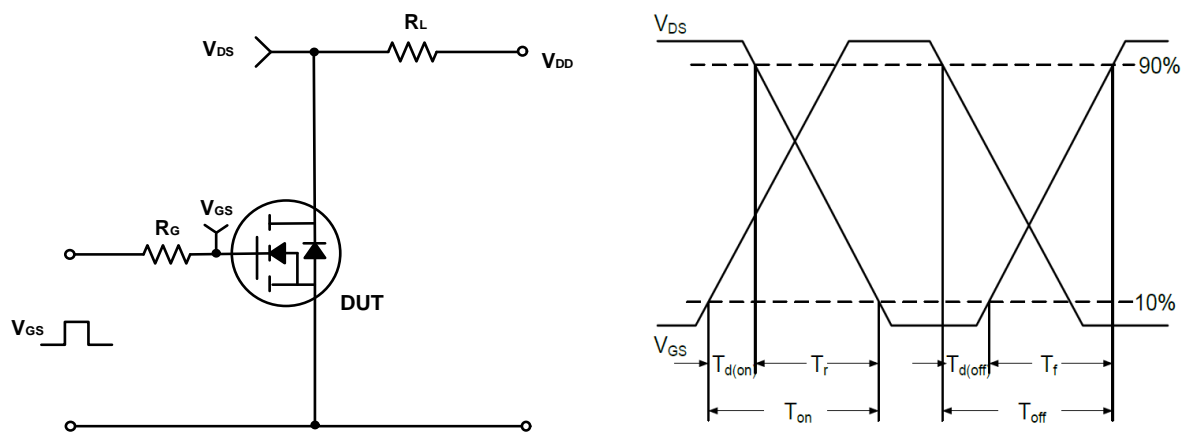


Figure B. Switching Test Circuit &amp; Waveforms

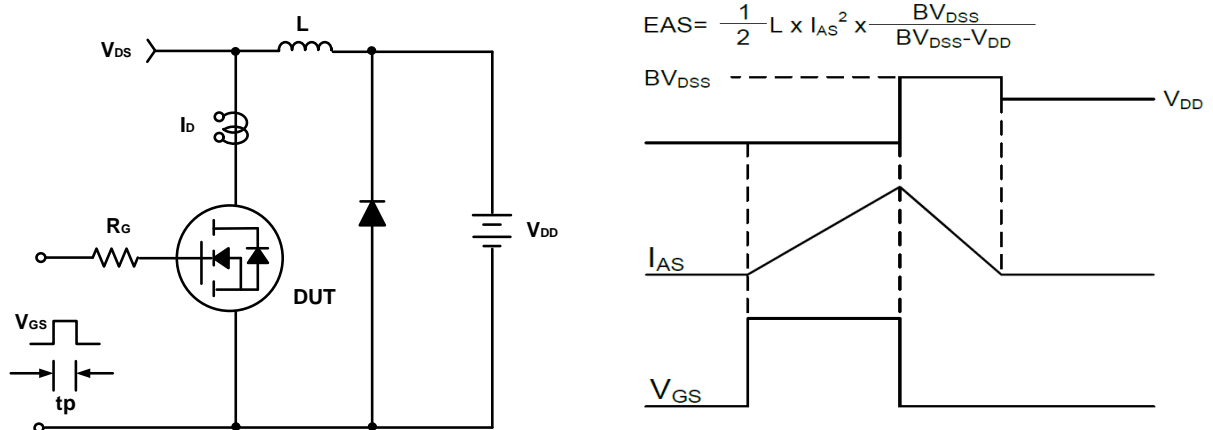
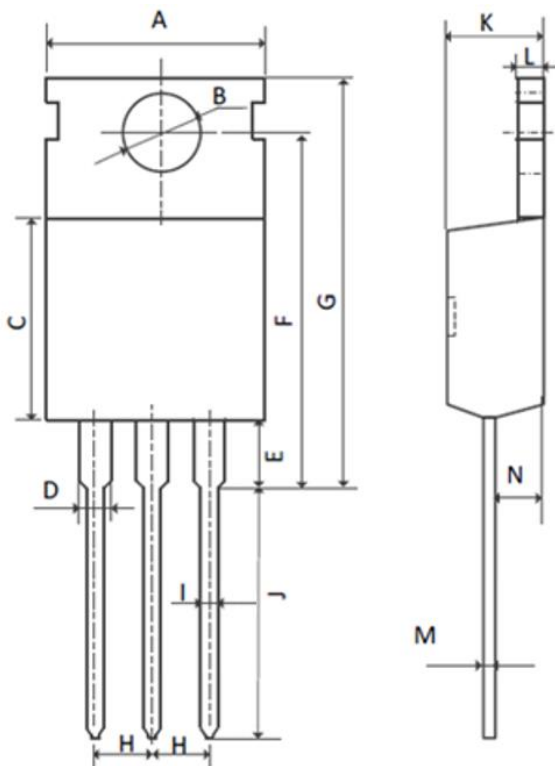


Figure C. Unclamped Inductive Switching Circuit &amp; Waveforms

## Mechanical Dimensions for TO-220

## COMMON DIMENSIONS

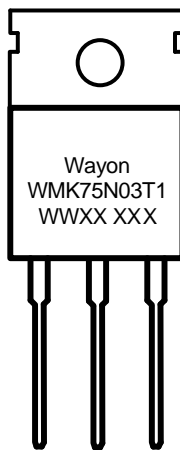


SYMBOL	MM	
	MIN	MAX
A	9.70	10.30
B	3.40	3.80
C	8.80	9.40
D	1.17	1.47
E	2.60	3.50
F	15.10	16.70
G	19.55MAX	
H	2.54REF	
I	0.70	0.95
J	9.35	11.00
K	4.30	4.77
L	1.20	1.45
M	0.40	0.65
N	2.20	2.60

## Ordering Information

Part	Package	Marking	Packing method
WMK75N03T1	TO-220	WMK75N03T1	Tube

## Marking Information



WMK75N03T1 = Device code

WWXX XXX= Date code

## Contact Information

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